

## DECLARATION FOR PATENT APPLICATION

As a below-named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated next to my name. I believe I am an original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled **Characterization of CYP 2D6 Genotypes**, the specification of which was filed on **07/10/03** as Application Serial No. **10/617,070**. I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, § 1.56(a).

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, § 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

10/411,954	04/11/03	Pending
60/371,819	04/11/02	Abandoned
<i>Application Serial No.</i>	<i>Filing Date</i>	<i>Patented, Pending or Abandoned</i>

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment or both, under § 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full Name of Sole or First Inventor: **Matt Neville**

Inventor's Signature: \_\_\_\_\_ Date: \_\_\_\_\_  
Residence: 54 Kingston Road, Oxford OX2 6RH, England Citizenship: Great Britain  
Post Office Address: 54 Kingston Road, Oxford OX2 6RH, England

Full Name of Second Joint Inventor: **Monika de Arruda Indig**

Inventor's Signature: *Monika de Arruda Indig* Date: 12/10/03  
Residence: 6618 Montclair Lane, Madison, WI 53711 Citizenship: United States of America  
Post Office Address: 6618 Montclair Lane, Madison, WI 53711

Full Name of Third Joint Inventor: **Feng Cao**

Inventor's Signature: *Feng Cao* Date: 12/10/03  
Residence: ~~2428 N. 111th Street, #6, Milwaukee, WI 53226~~ *617 Bradford Way, Hartland, WI 53029* Citizenship: People's Republic of China  
Post Office Address: ~~2428 N. 111th Street, #6, Milwaukee, WI 53226~~ *617 Bradford Way, Hartland, WI 53029*

Full Name of Fourth Joint Inventor: **Mary C. Oldenburg**

Inventor's Signature: *Mary C. Oldenburg* Date: 12/10/03  
Residence: 30 North Third Street, Madison, WI 53704 Citizenship: ~~People's Republic of China~~ *USA*  
Post Office Address: 30 North Third Street, Madison, WI 53704

DECLARATION FOR PATENT APPLICATION (cont.)

Full Name of Fifth Joint Inventor: James A. Koelbl

Inventor's Signature: James A. Koelbl  
 Residence: 1033 Tilda Trail, Cross Plains, WI 53528  
 Post Office Address: 1033 Tilda Trail, Cross Plains, WI 53528

Date: 12/11/2003  
 Citizenship: United States of America

Full Name of Sixth Joint Inventor: Brian D. Aizenstein

Inventor's Signature: \_\_\_\_\_  
 Residence: 230 Glenway Street, Madison, WI 53705  
 Post Office Address: 230 Glenway Street, Madison, WI 53705

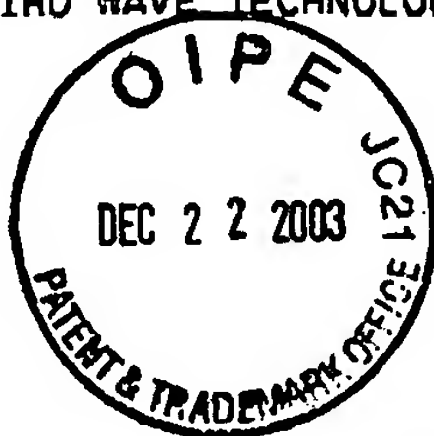
Date: \_\_\_\_\_  
 Citizenship: United States of America

Full Name of Seventh Joint Inventor: Keith Davey

Inventor's Signature: Keith Davey  
 Residence: 10 Nantucket Court, Madison, WI 53719  
 Post Office Address: 10 Nantucket Court, Madison, WI 53719

Date: 12/15/2003  
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**PATENT**  
Attorney Docket No.: **FORS-08195**  
Page 1 of 2

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60/371,819

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Full Name of Sole or First Inventor: **Matt Neville**

Inventor's Signature: [Signature] Date: 11/12/03  
Residence: 54 Kingston Road, Oxford OX2 6RH, England Citizenship: Great Britain  
Post Office Address: 54 Kingston Road, Oxford OX2 6RH, England

Full Name of Second Joint Inventor: **Monika de Arruda Indig**

Inventor's Signature: \_\_\_\_\_ Date: \_\_\_\_\_  
Residence: 6618 Montclair Lane, Madison, WI 53711 Citizenship: United States of America  
Post Office Address: 6618 Montclair Lane, Madison, WI 53711

Full Name of Third Joint Inventor: **Feng Cao**

Inventor's Signature: \_\_\_\_\_ Date: \_\_\_\_\_  
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Post Office Address: 2428 N. 111th Street, #6, Milwaukee, WI 53226

Full Name of Fourth Joint Inventor: **Mary C. Oldenburg**

Inventor's Signature: \_\_\_\_\_ Date: \_\_\_\_\_  
Residence: 30 North Third Street, Madison, WI 53704 Citizenship: People's Republic of China  
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## DECLARATION FOR PATENT APPLICATION (cont.)

PATENT  
Attorney Docket No.: FORS-08195  
Page 2 of 2

Full Name of Fifth Joint Inventor: James A. Koelbl

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Date: \_\_\_\_\_

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Full Name of Sixth Joint Inventor: Brian D. Alzenstein

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Citizenship: United States of America

Full Name of Seventh Joint Inventor: Keith Davey

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